

Abstract:

An adhesion promoter which comprises from 2 to 100% by weight of a copolymer which contains the following monomer units:

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a) from 70 to 99.9% by weight of monomer units which derive from vinyl compounds selected from acrylic acid derivatives, methacrylic acid derivatives, and vinylaromatics, and also

10 b) from 0.1 to 30% by weight of monomer units which contain a functional group selected from a carboxylic anhydride group, an epoxy group, and an oxazoline group,

is used for production of a bond between

- 15 I. a layer composed of a polyamide molding compound, and
II. a part composed of an ABS molding composition.